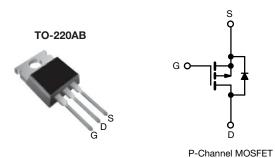


Power MOSFET



PRODUCT SUM	MARY	
V _{DS} (V)	-10	00
$R_{DS(on)}(\Omega)$	V _{GS} = -10 V	0.60
Q _g max. (nC)	18	3
Q _{gs} (nC)	3.0	0
Q _{gd} (nC)	9.0	0
Configuration	Sing	gle

FEATURES

- Dynamic dv/dt rating
- · Repetitive avalanche rated
- P-channel
- 175 °C operating temperature
- · Fast switching
- · Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRF9520PbF
Lead (Pb)-free and halogen-free	IRF9520PbF-BE3

ABSOLUTE MAXIMUM RATINGS (T_C	= 25 °C, unle	ess otherwis	e noted)			
PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-source voltage		V _{DS}	-100			
Gate-source voltage		V _{GS}	± 20	V		
Continuous drain current	V _{GS} at 10 V	$T_{\rm C} = 25 ^{\circ}{\rm C}$ $T_{\rm C} = 100 ^{\circ}{\rm C}$		-6.8		
Continuous drain current	V _{GS} at 10 V	T _C = 100 °C	I _D	-4.8	А	
Pulsed drain current ^a			-27			
Linear derating factor			0.40	W/°C		
Single pulse avalanche energy b		E _{AS}	300	mJ		
Repetitive avalanche current ^a		I _{AR}	-6.8	А		
Repetitive avalanche energy ^a		E _{AR}	6.0	mJ		
Maximum power dissipation $T_C = 25 ^{\circ}C$		P _D	60	W		
Peak diode recovery dV/dt ^c		dv/dt	-5.5	V/ns		
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +175	°C	
Soldering recommendations (peak temperature) d For 10 s		300]			
Mounting towns	6.22.04.1	40 oorow		10 lbf ⋅ in		
Mounting torque	6-32 or M3 screw			1.1	N⋅m	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. V_{DD} = -25 V, starting T_J = 25 °C, L = 9.7 mH, R_q = 25 Ω , I_{AS} = -6.8 A (see fig. 12)
- c. $I_{SD} \le -6.8 \text{ A}$, $di/dt \le 110 \text{ A/}\mu\text{s}$, $V_{DD} \le V_{DS}$, $T_J \le 175 \text{ °C}$
- d. 1.6 mm from case



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THERMAL RESISTANCE RAT	INGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R _{thJA}	-	62	
Case-to-sink, flat, greased surface	R _{thCS}	0.50	-	°C/W
Maximum junction-to-case (drain)	R _{thJC}	-	2.5	

PARAMETER	SYMBOL	TEST	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0$	Ο V, I _D = -250 μA	-100	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	to 25 °C, I _D = -1 mA	1	-0.10	-	V/°C
Gate-source threshold voltage	V _{GS(th)}	V _{DS} = \	/ _{GS} , I _D = -250 μA	-2.0	-	-4.0	V
Gate-source leakage	I _{GSS}	V	_{GS} = ± 20 V	-	-	± 100	nA
Zero gate voltage drain current	I _{DSS}		V _{DS} = -100 V, V _{GS} = 0 V		-	-100	μA
Zero gate voltage drain current	צצעי		$V_{GS} = 0 \text{ V}, T_{J} = 150 ^{\circ}\text{C}$	1	-	-500	μΛ
Drain-source on-state resistance	R _{DS(on)}	$V_{GS} = -10 \text{ V}$	I _D = -4.1 A ^b	ı	-	0.60	Ω
Forward transconductance	9 _{fs}	V _{DS} = -	50 V, I _D = -4.1 A ^b	2.0	-	-	S
Dynamic							
Input capacitance	C_{iss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = -25 \text{ V},$ $f = 1.0 \text{ MHz}, \text{ see fig. 5}$		1	390	-	pF
Output capacitance	C _{oss}			ı	170	-	
Reverse transfer capacitance	C_{rss}			1	45	-]
Total gate charge	Q_g			ı	-	18	
Gate-source charge	Q_{gs}	$V_{GS} = -10 \text{ V}$	I _D = -6.8 A, V _{DS} = -80 V, see fig. 6 and 13 ^b	-	-	3.0	nC
Gate-drain charge	Q_{gd}		oco ng. o ana ro	-	-	9.0]
Turn-on delay time	t _{d(on)}			=	9.6	-	
Rise time	t _r	V _{DD} = -	$V_{DD} = -50 \text{ V}, I_D = -6.8 \text{ A},$		29	-	ns
Turn-off delay time	t _{d(off)}	R_g = 18 Ω , R_D = 7.1 Ω , see fig. 10 b		-	21	-	
Fall time	t _f			-	25	-	
Gate input resistance	R _g	f = 1 MHz, open drain		0.8	-	3.9	Ω
Internal drain inductance	L _D		6 mm (0.25") from		4.5	-	n ^U
Internal source inductance	L _S	package and center of die contact		ı	7.5	-	- nH
Drain-Source Body Diode Characteristic	cs						
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	-6.8	- A
Pulsed diode forward current ^a	I _{SM}			-	-	-27	
Body diode voltage	V_{SD}	$T_J = 25 ^{\circ}\text{C}, I_S = -6.8 \text{A}, V_{GS} = 0 \text{V}^{ \text{b}}$		-	-	-6.3	V
Body diode reverse recovery time	t _{rr}	T _J = 25 °C, I _F = -6.8 A, dI/dt = 100 A/μs b		-	98	200	ns
Body diode reverse recovery charge	Q _{rr}			-	0.33	0.66	μC
Forward turn-on time	t _{on}	Intrinsic turi	n-on time is negligible (turn	on is do	minated b	y L _S and	L _D)

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width \leq 300 µs; duty cycle \leq 2 %



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

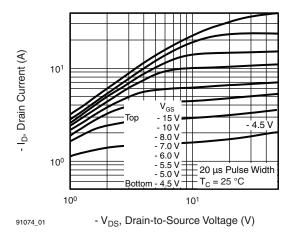


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

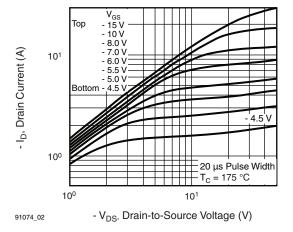


Fig. 2 - Typical Output Characteristics, $T_C = 175$ °C

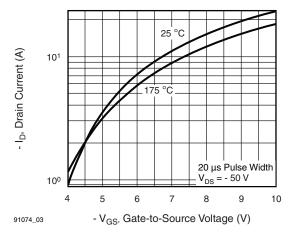


Fig. 3 - Typical Transfer Characteristics

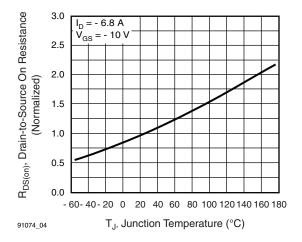


Fig. 4 - Normalized On-Resistance vs. Temperature

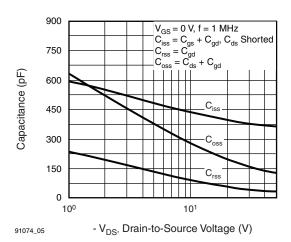


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

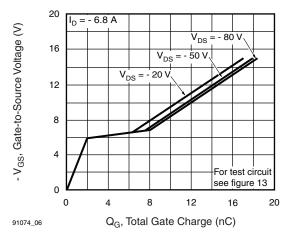


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



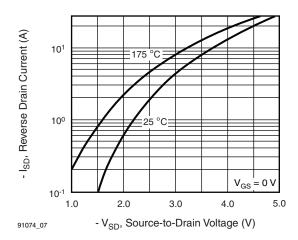


Fig. 7 - Typical Source-Drain Diode Forward Voltage

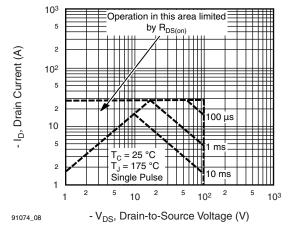


Fig. 8 - Maximum Safe Operating Area

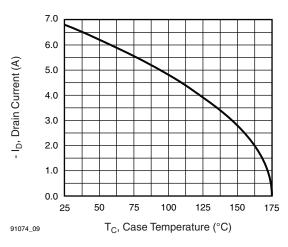


Fig. 9 - Maximum Drain Current vs. Case Temperature

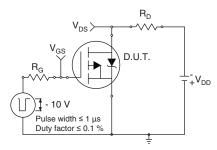


Fig. 10a - Switching Time Test Circuit

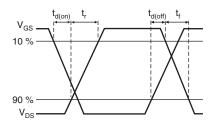


Fig. 10b - Switching Time Waveforms

Document Number: 91074

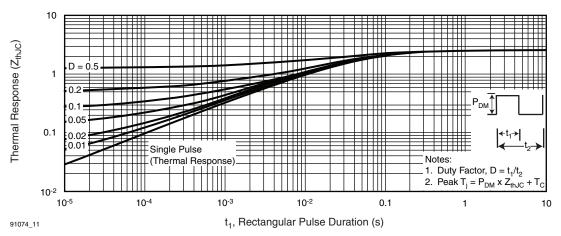


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



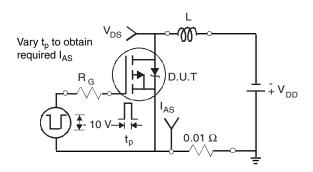


Fig. 12a - Unclamped Inductive Test Circuit

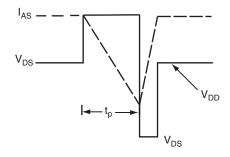


Fig. 12b - Unclamped Inductive Waveforms

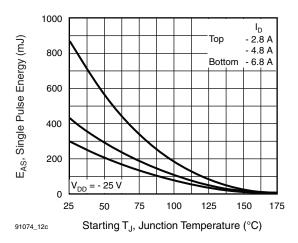


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

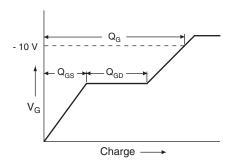


Fig. 13a - Basic Gate Charge Waveform

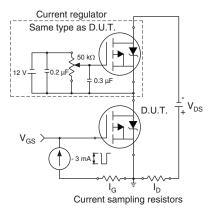
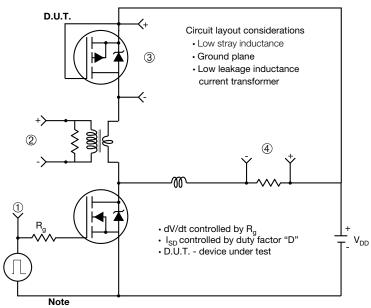


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



• Compliment N-Channel of D.U.T. for driver

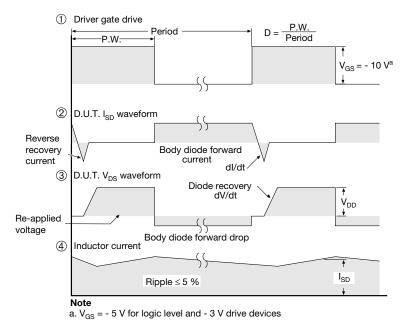


Fig. 14 - For P-Channel

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TO-220-1



DIM.	MILLIM	METERS	INC	HES
	MIN.	MAX.	MIN.	MAX.
Α	4.24	4.65	0.167	0.183
b	0.69	1.02	0.027	0.040
b(1)	1.14	1.78	0.045	0.070
С	0.36	0.61	0.014	0.024
D	14.33	15.85	0.564	0.624
E	9.96	10.52	0.392	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.10	6.71	0.240	0.264
J(1)	2.41	2.92	0.095	0.115
L	13.36	14.40	0.526	0.567
L(1)	3.33	4.04	0.131	0.159
ØΡ	3.53	3.94	0.139	0.155
Q	2.54	3.00	0.100	0.118

Note

DWG: 6031

• $M^* = 0.052$ inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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